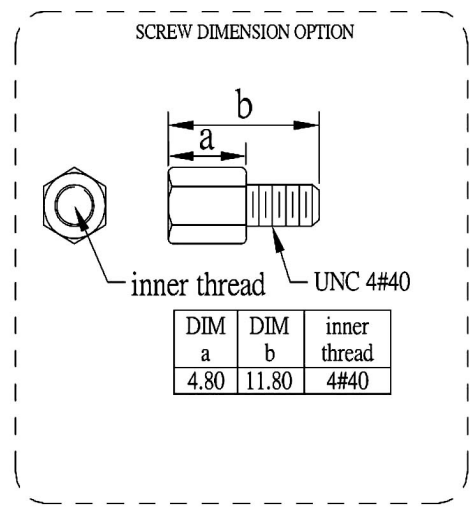


MATERIAL  
 HOUSING : HIGH TEMPERATURE HOUSING  
 LCP (UL94V-0)WITHSTANDS IR AND  
 VPR SOLDERING METHODS.  
 CONTACTS : PHOSPHOR BRONZE.  
 PLATING : SELECTIVE GOLD PLATED.

SPECIFICATION  
 CURRENT RATING : 3 AMP.  
 INSULATOR RESISTANCE 5000MΩ MIN. AT DC 500V.  
 CONTACT RESISTANCE : 20MΩ MAX. AT DC 100mA.  
 OPERATING TEMPERATURE : -65°C~+125°C.  
 MAX PROCESSING TEMPERATURE: 260±10°C FOR 3-5 SECONDS.



RoHS Compliant		<b>玄茂科技股份有限公司</b> <b>HSUAN MAO TECHNOLOGY CO., LTD.</b>	
APPD. 核准 DWG. 製圖 DATE 制表日 2018/05/16	SCALE 比例 參考 UNIT 單位 M M PAGE 張數 1 OF 1	TOLERANCE .0±0.30 .00±0.20 .000±.050 .0000±.0000 ANG.±3°	PART NAME 品名 D-SUB PCB R/A FOR NOTEBOOK SMT TYPE 9P FEMALE THREAD INSERT 4-40UNC WITH BOARDLOCK FIX SCREWS 4.8*11.8mm SELECTIVE GOLD PLATING BLACK COLOR MATERIAL: LCP (POST SPACING=15.9mm) ROHS
		SIZE 紙張尺寸 A 4 REV. 版次 A	PART NO. 料號 C0527-09FBCXSBN